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TECHNOLOGY CENTER R3700

ATTORNEY DOCKET NO. 025311-0115

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Applicant: Yashimasa KAWASE

Title: WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

Appl. No.: 10/066,783

Filing Date: February 6, 2002

Examiner: G. Wilson

Art Unit: 3749

S/A
JH
2-28-03

AMENDMENT AND REPLY UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed December 31, 2002, please amend the application as follows and consider the following remarks.

In the Claims:

In accordance with 37 C.F.R. § 1.121, please substitute for claim 1, the following rewritten version of the same claim, as amended. The changes are shown explicitly in the attached "Versions with Markings to Show Changes Made."

A
1. (Once Amended) A wafer heat-treatment system for processing a wafer by a high-temperature heat-treatment process and cooling the heat-treated wafer, said wafer heat-treatment system comprising:

walls surrounding a closed space enclosing the wafer and having a hollow sealing a gas in said walls; and

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a pressure-regulating unit connecting to said hollow for regulating pressure in said hollow.